

[illegible]

TMAX-1770-XXX-M M lded P e I d c

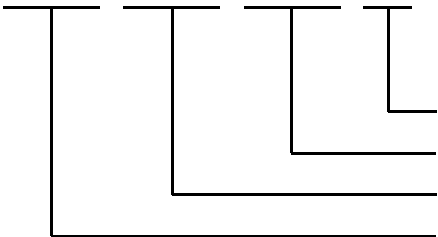
Features

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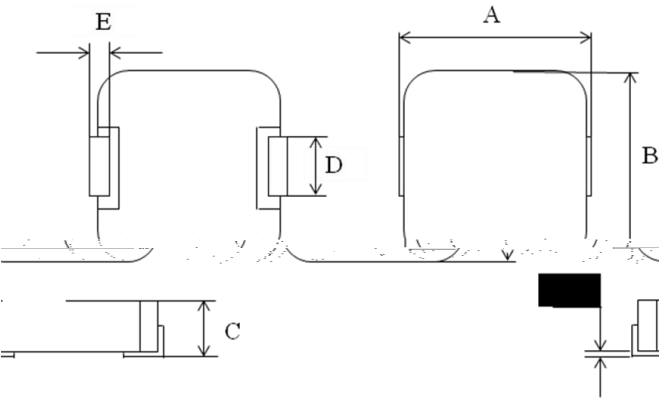
Applications

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Product Description

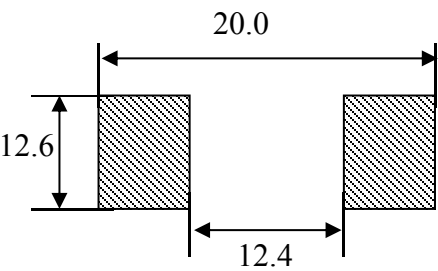


Dimensions



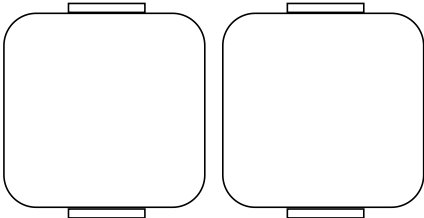
	17.5 Max.
	17.15 Max.
	7.0 Max.
	11.8±0.3
	2.5±0.5
	0~0.30

Recommend Land Pattern Dimensions



Marking

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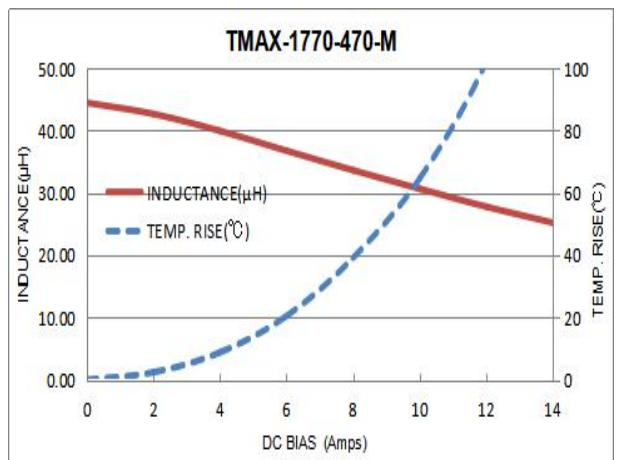
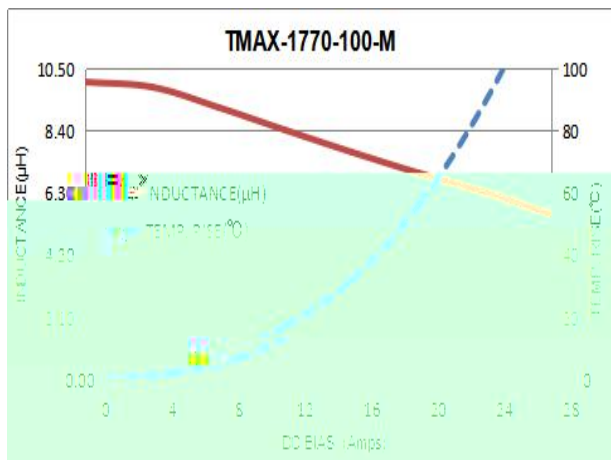
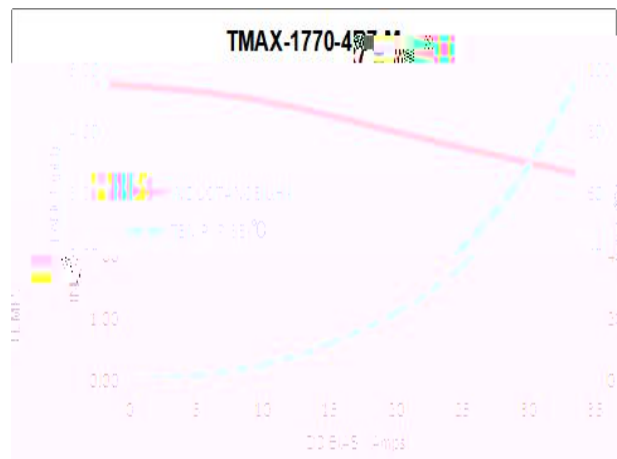
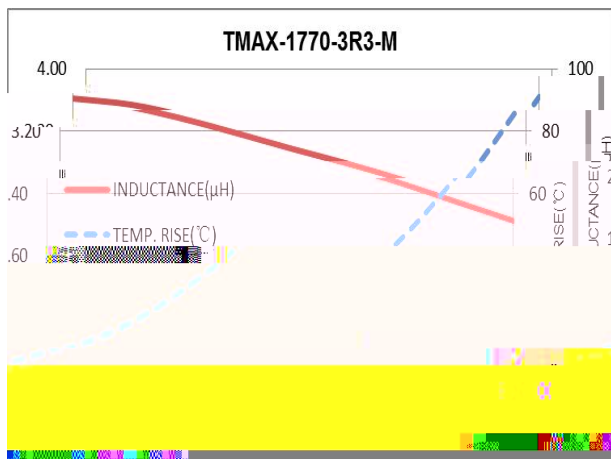


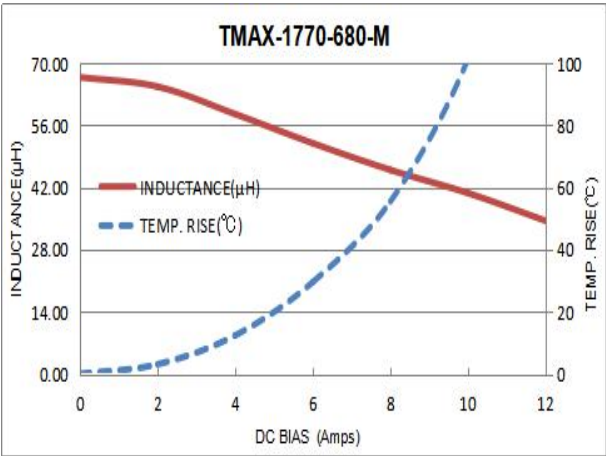
$I \quad a \quad : 0.1 \ H$

Notes:

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Inductance and Temperature Rise vs. DC Current





Reliability:

Item	Test Method	Specification and Requirement
	<div>±</div> <div>± °C ±</div>	
		<div>±</div>



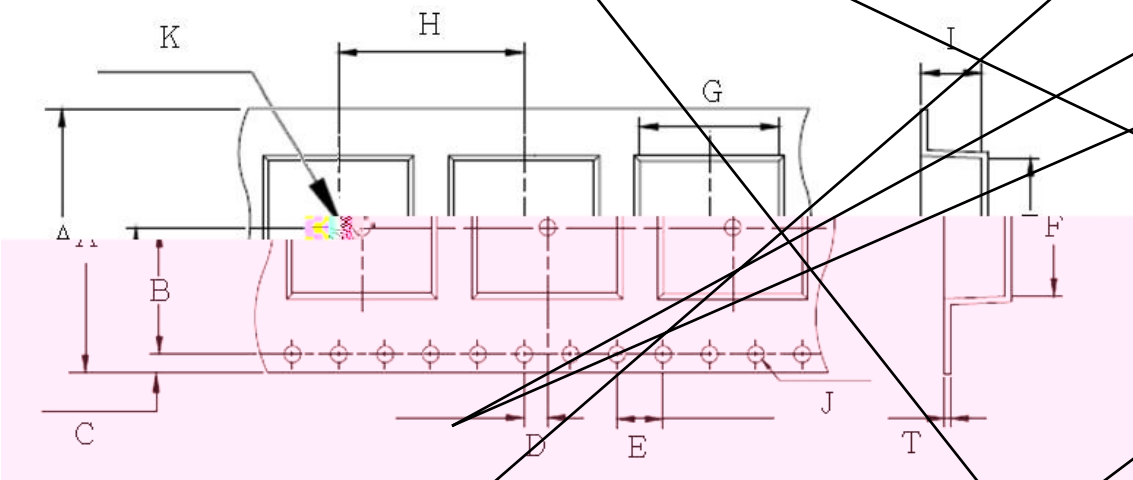
Reliability:

Item	Test Method	Specification and Requirement
	<div><div><div>±</div><div>→</div></div><div><div>±</div><div>→</div></div><div><div>→</div><div>±</div></div><div><div>±</div><div>→</div></div></div>	±
	±	
	±	
	±	
	±	



R A0
C N :

Packaging Dimensions



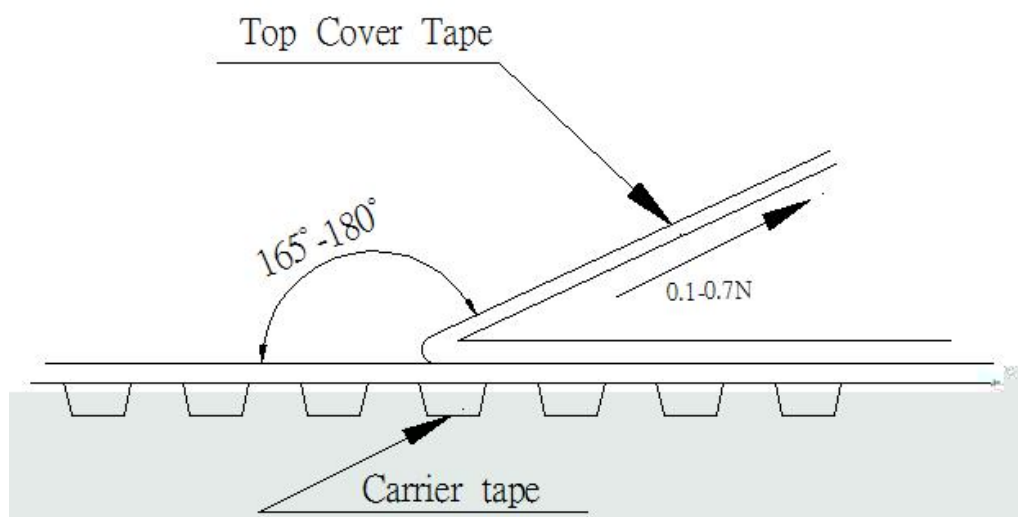
±	±	±	±	±	±
±	±	±	±	±	±

Reel Dimensions

±	±	

Peeling of top cover tape

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Reflow Profile

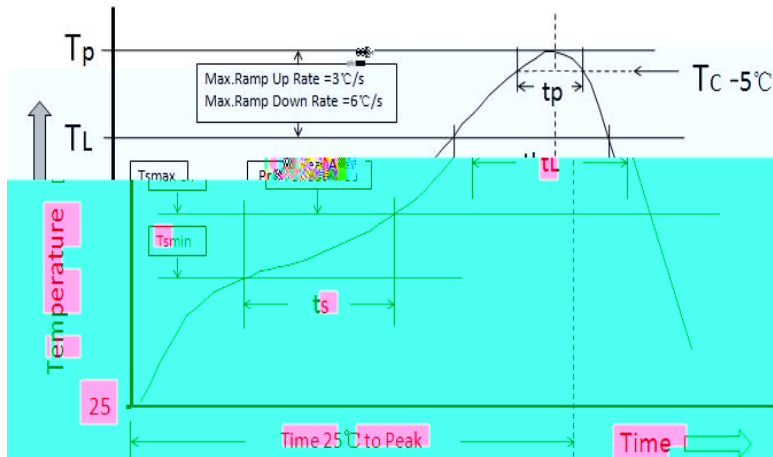


Table1-StandardSnPb Solder(T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<	°C	°C
≧	°C	°C

Table2-Lead(Pb)Free Solder(T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<	°C	°C	°C
	°C	°C	°C
	°C	°C	°C

Reference JDEC J-STD-020(latest revision)

Profile Feature	Standard SnPb solder	Lead(Pb) Free Solder
	°C	°C
	°C	°C
	°C	°C
	°C	°C
°C		
	°C	°C
°C		



Numbers of taping



Label marking



Production Label



Shipping Label



Care note for use

➤ Storage Condition

➤ Use Temperature





Care note for Safety

